

FIN1017

3.3V LVDS, 1-Bit, High-Speed Differential Driver

Features

- Greater than 600Mbps Data Rate
- 3.3V Power Supply Operation
- 0.5ns Maximum Differential Pulse Skew
- 1.5ns Maximum Propagation Delay
- Low Power Dissipation
- Power-Off Protection
- Meets or Exceeds the TIA/EIA-644 LVDS Standard
- Flow-Through Pinout Simplifies PCB Layout
- 8-Lead SOIC and US8 Packages Save Space

Description

This single driver is designed for high-speed interconnects utilizing Low Voltage Differential Signaling (LVDS) technology. The driver translates LVTTTL signal levels to LVDS levels with a typical differential output swing of 350mV, which provides low EMI at ultra-low power dissipation even at high frequencies. This device is ideal for high-speed transfer of clock or data.

The FIN1017 can be paired with its companion receiver, the FIN1018, or with any other LVDS receiver.

Ordering Information

Part Number	Operating Temperature Range	Package	Packing Method
FIN1017MX	-40 to +85°C	8-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150inch Narrow	Tape and Reel
FIN1017K8X	-40 to +85°C	8-Lead US8, JEDEC MO-187, Variation CA 3.1mm Wide	Tape and Reel

Pin Configuration

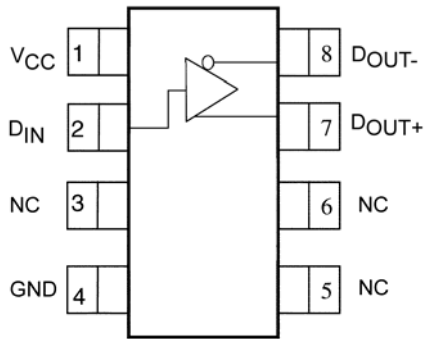


Figure 1. SOIC

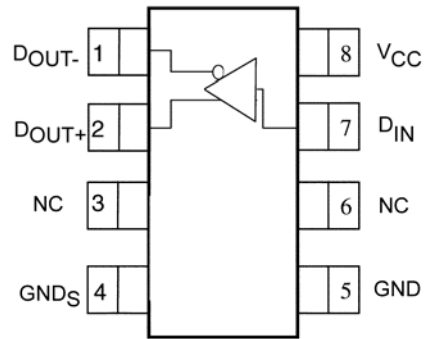


Figure 2. US-8 (Top View)⁽¹⁾

Note:

1. Ground pins 4 and 5 for optimum performance.

Pin Definitions

Pin# US-8	Pin# SOIC	Name	Description
7	2	D _{IN}	LVTTTL Data Input
2	7	D _{OUT+}	Non-inverting Driver Output
1	8	D _{OUT-}	Inverting Driver Output
8	1	V _{CC}	Power Supply
4, 5	4	GND / GND _S	Ground
3, 6	3, 5, 6	NC	No Connect

Function Table

Input	Outputs	
D _{IN}	D _{OUT+}	D _{OUT-}
LOW	LOW	HIGH
HIGH	HIGH	LOW
OPEN	LOW	HIGH

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Min.	Max.	Unit
V _{CC}	Supply Voltage	-0.5	+4.6	V
D _{IN}	DC Input Voltage	-0.5	+6.0	V
D _{OUT}	DC Output Voltage	-0.5	+4.7	V
I _{OSD}	Driver Short-Circuit Current, Continuous		10	mA
T _{STG}	Storage Temperature Range	-65	+150	°C
T _J	Max Junction Temperature		+150	°C
T _L	Lead Temperature (Soldering, 10 Seconds)		+260	°C
ESD	Human Body Model, JESD22-A114		6500	V
	Bus Pins D _{OUT+} /D _{OUT-} to GND		10500	
	Machine Model, JESD22-A115		350	

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Max.	Unit
V _{CC}	Supply Voltage	3.0	3.6	V
V _{IN}	Input Voltage	0	V _{CC}	V
T _A	Operating Temperature	-40	+85	°C

DC Electrical Characteristics

Over-supply voltage and operating temperature ranges, unless otherwise specified. All typical values are at $T_A = 25^\circ\text{C}$ and with $V_{CC} = 3.3\text{V}$.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
V_{OD}	Output Differential Voltage	$R_L = 100\ \Omega$, See Figure 3	250	350	450	mV
ΔV_{OD}	V_{OD} Magnitude Change from Differential LOW-to-HIGH				25	mV
V_{OS}	Offset Voltage		1.125	1.250	1.375	V
ΔV_{OS}	Offset Magnitude Change from Differential LOW-to-HIGH				25	mV
I_{OFF}	Power-Off Output Current	$V_{CC} = 0\text{V}$, $V_{OUT} = 0\text{V}$ or 3.6V			± 20	mA
I_{OS}	Short-Circuit Output Current	$V_{OUT} = 0\text{V}$			-8	mA
		$V_{OD} = 0\text{V}$			± 8	
V_{IH}	Input HIGH Voltage		2		V_{CC}	V
V_{IL}	Input LOW Voltage		GND		0.8	V
I_{IN}	Input Current	$V_{IN} = 0\text{V}$ or V_{CC}			± 20	mA
$I_{I(OFF)}$	Power-Off Input Current	$V_{CC} = 0\text{V}$, $V_{IN} = 0\text{V}$ or 3.6V			± 20	mA
V_{IK}	Input Clamp Voltage	$I_{IK} = -18\text{mA}$	-1.5			V
I_{CC}	Power Supply Current	No Load, $V_{IN} = 0\text{V}$ or V_{CC}			8	mA
		$R_L = 100\ \Omega$, $V_{IN} = 0\text{V}$ or V_{CC}			10	mA
C_{IN}	Input Capacitance			4		pF
C_{OUT}	Output Capacitance			6		pF

AC Electrical Characteristics

Over-supply voltage and operating temperature ranges, unless otherwise specified. All typical values are at $T_A = 25^\circ\text{C}$ and with $V_{CC} = 3.3\text{V}$.

Symbol	Parameter	Test Conditions	Min.	Max.	Units
t_{PLHD}	Differential Propagation Delay, LOW-to-HIGH	$R_L = 100\ \Omega$, $C_L = 10\text{pF}$, see Figure 4 and Figure 5	0.5	1.5	ns
t_{PHLD}	Differential Propagation Delay, HIGH-to-LOW		0.5	1.5	ns
t_{TLHD}	Differential Output Rise Time (20% to 80%)		0.4	1.0	ns
t_{THLD}	Differential Output Fall Time (80% to 20%)		0.4	1.0	ns
$t_{SK(P)}$	Pulse Skew $ t_{PLH} - t_{PHL} $			0.5	ns
$t_{SK(PP)}$	Part-to-Part Skew ⁽²⁾			1.0	ns

Note:

- $t_{SK(PP)}$ is the magnitude of the difference in propagation delay times between any specified terminals of two devices switching in the same direction (either LOW-to-HIGH or HIGH-to-LOW) when both devices operate with the same supply voltage, same temperature, and have identical test circuits.

Test Diagrams

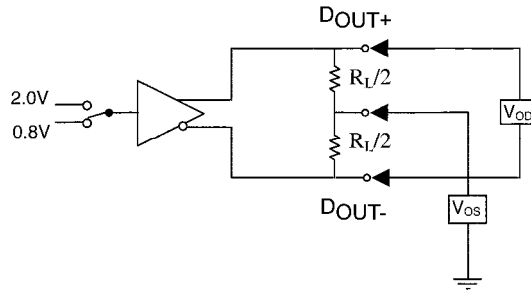


Figure 3. Differential Driver DC Test Circuit

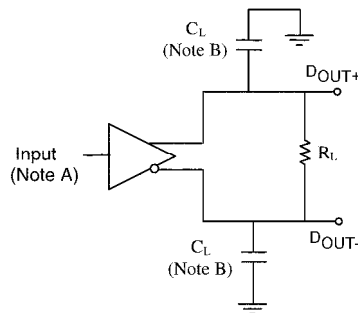


Figure 4. Differential Driver Propagation Delay and Transition Time Test Circuit

Notes:

Note A: All input pulses have frequency = 10MHz, t_r or t_f = 2ns.

Note B: C_L includes all probe and fixture capacitances.

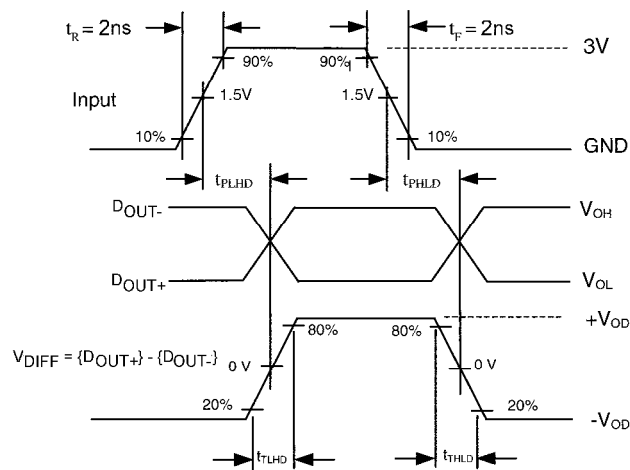


Figure 5. AC Waveforms

Typical Performance Characteristics

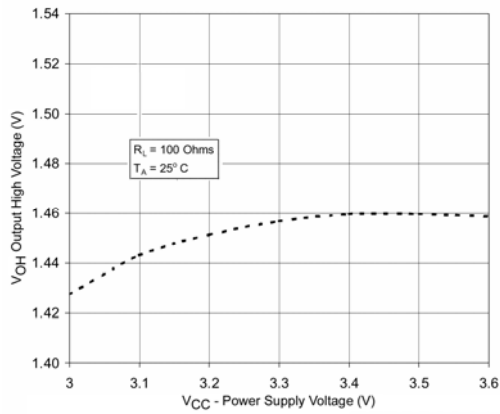


Figure 6. Output High Voltage vs. Power Supply Voltage

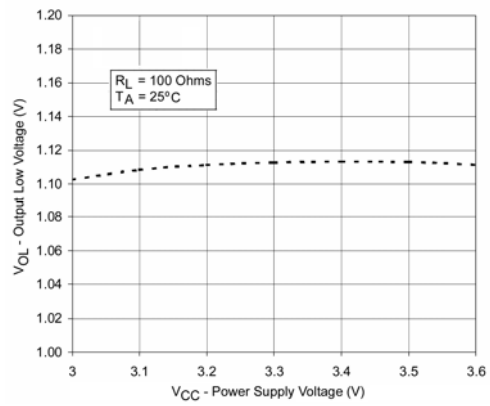


Figure 7. Output Low Voltage vs. Power Supply Voltage

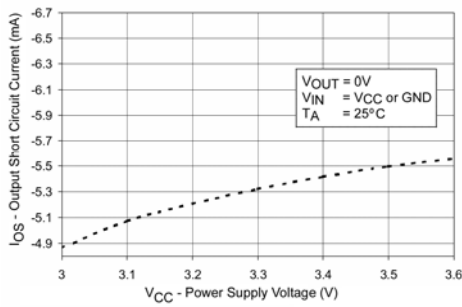


Figure 8. Output Short Circuit Current vs. Power Supply Voltage

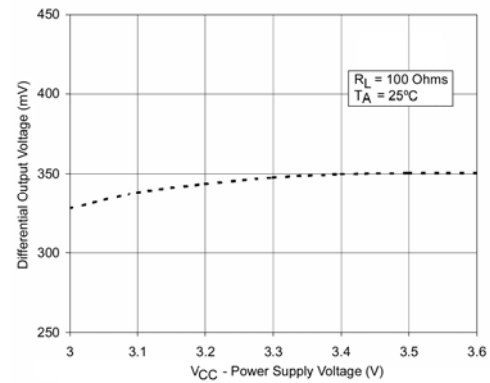


Figure 9. Differential Output Voltage vs. Power Supply Voltage

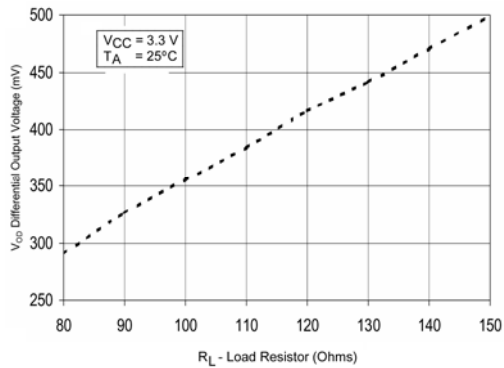


Figure 10. Differential Output Voltage vs. Load Resistor

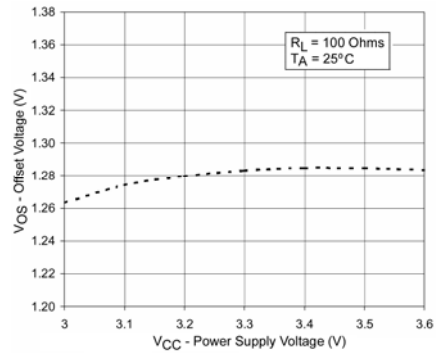


Figure 11. Offset Voltage vs. Power Supply Voltage

Typical Performance Characteristics

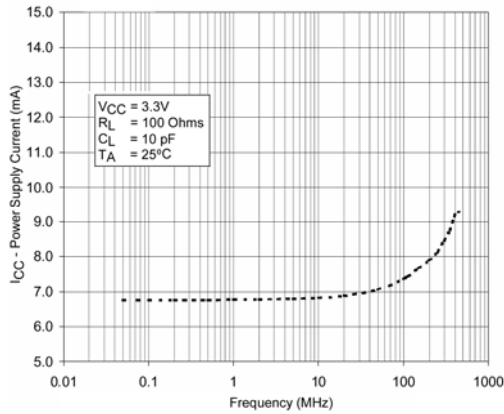


Figure 12. Power Supply Current vs. Frequency

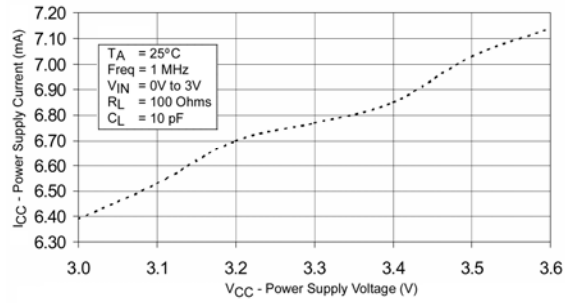


Figure 13. Power Supply Current vs. Power Supply Voltage

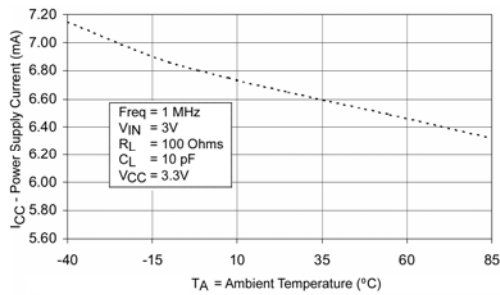


Figure 14. Power Supply Current vs. Ambient Temperature

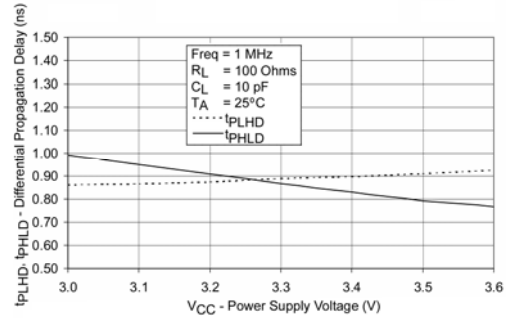


Figure 15. Differential Propagation Delay vs. Power Supply

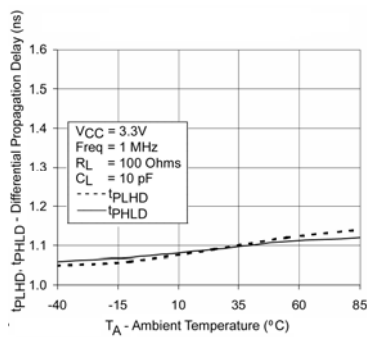


Figure 16. Differential Propagation Delay vs. Ambient Temperature

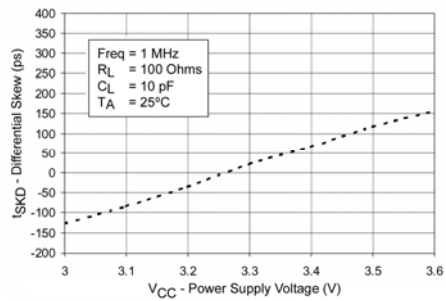


Figure 17. Differential Pulse Skew ($t_{PLH} - t_{PHL}$) vs. Power Supply Voltage

Typical Performance Characteristics

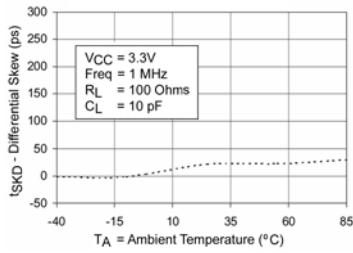


Figure 18. Differential Pulse Skew ($t_{PLH} - t_{PHL}$) vs. Ambient Temperature

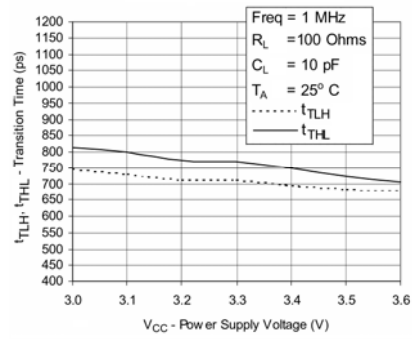


Figure 19. Transition Time vs. Power Supply Voltage

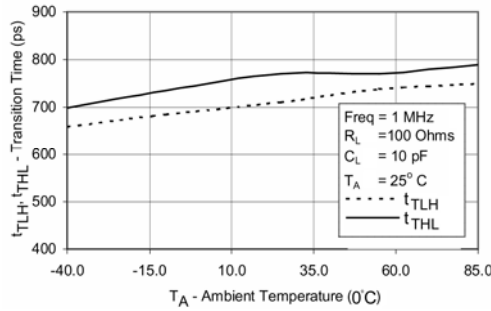


Figure 20. Transition Time vs. Ambient Temperature

Physical Dimensions

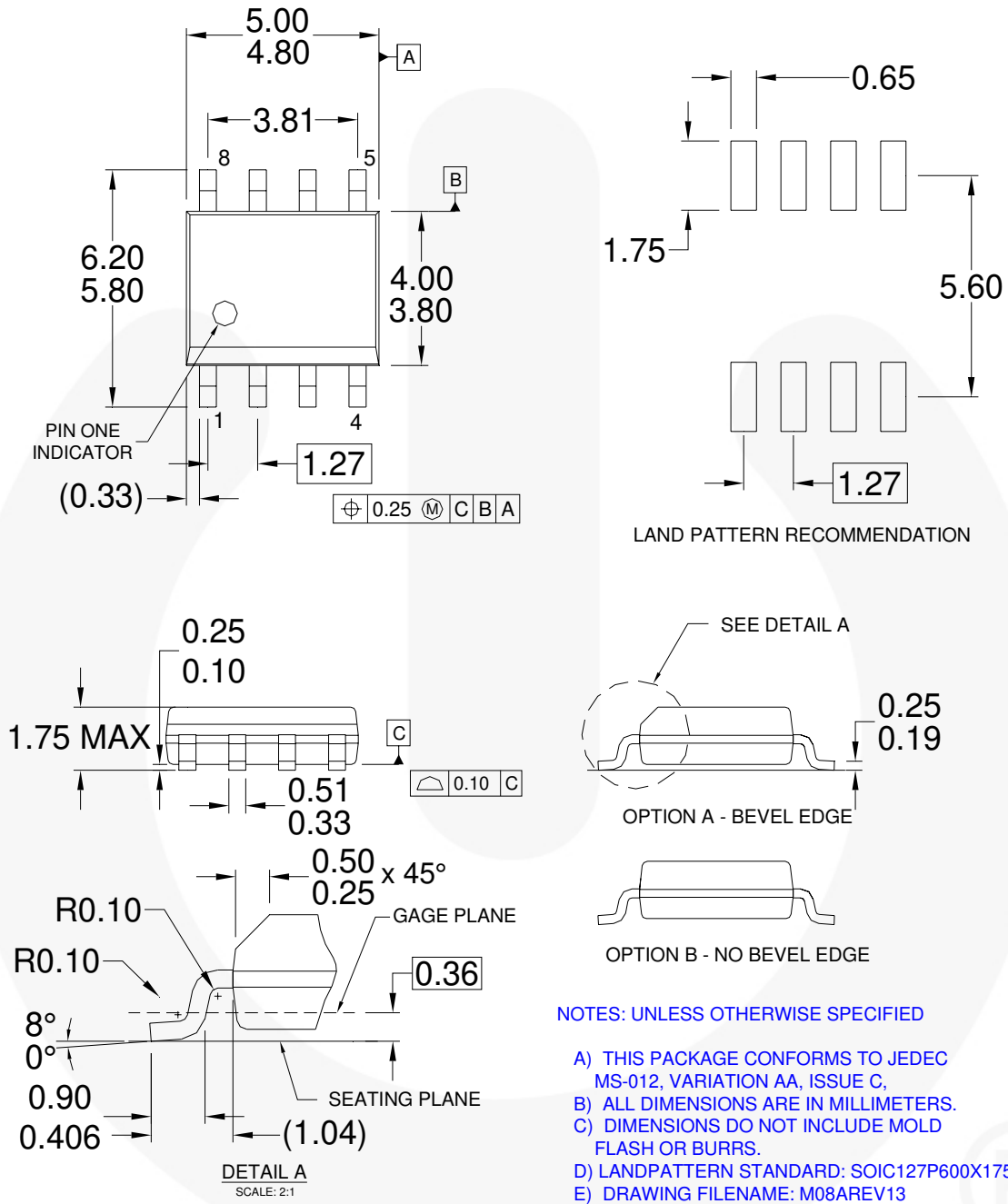
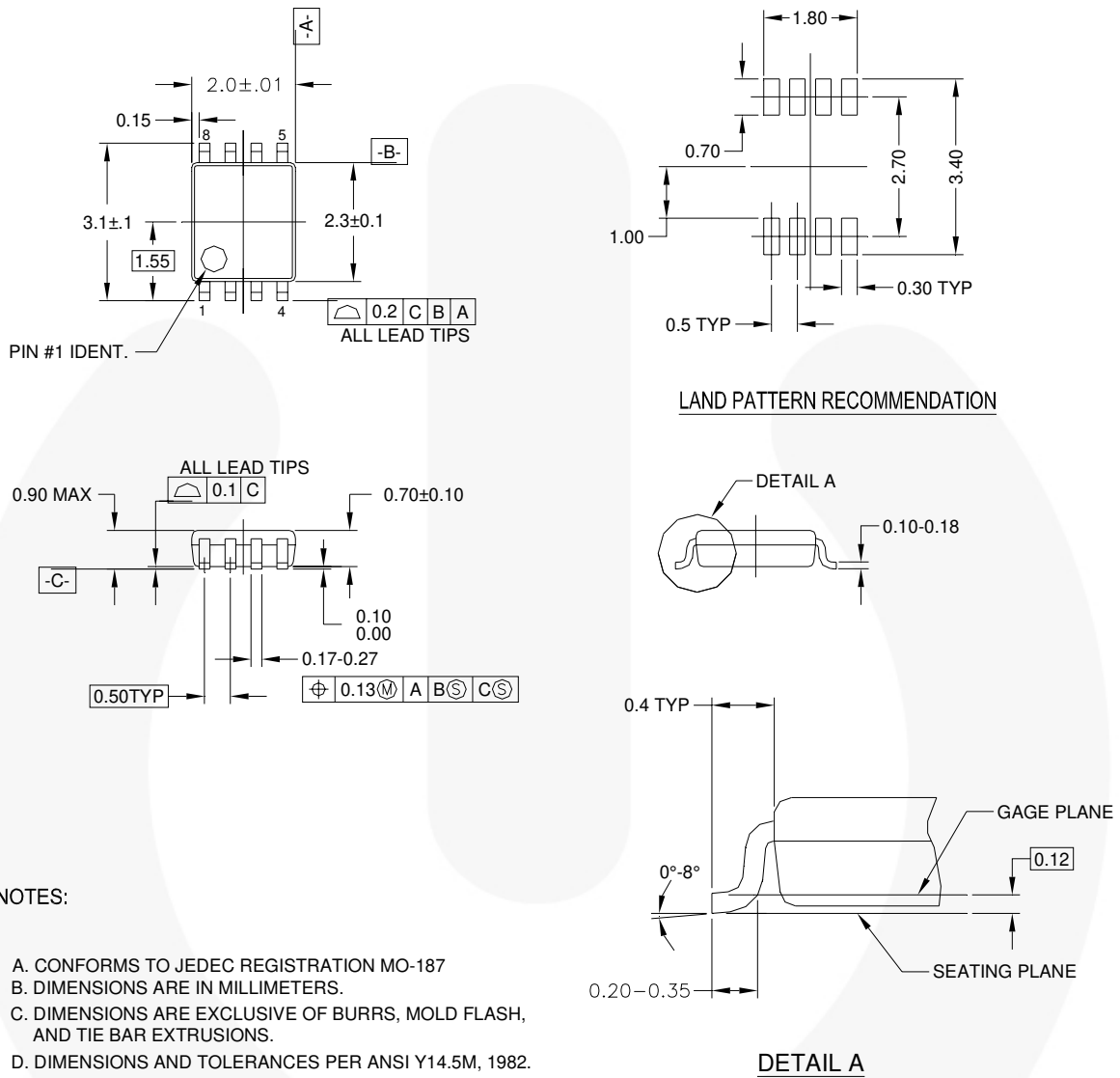


Figure 21. 8-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150inch Narrow

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Physical Dimensions



MAB08AREVC

Figure 22. 8-Lead US8, JEDEC MO-187, Variation CA 3.1mm Wide

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